



Innodisk Corporate Investor Conference (Symbol: 5289)

Randy Chien, Chairman 2026.08.27

DISCLAIMER

This file and the financial information and forecast information are based on information obtained by the company from internal and external sources. The actual operating results and financial conditions of the company may differ from these predictive sets of information due to various uncontrollable factors.

The viewpoints in this file reflects the company's opinion on the future by the current date. If there are any changes or adjustment in the future, the company is not responsible for notifying the reader or updating the content.

AGENDA

- Company Profile and Overview
- Market Trend and Product Strategy
- AI in Action Global Campaign
- ESG Commitment
- Financial Information
- Q&A

COMPANY PROFILE & OVERVIEW

CORPORATE OVERVIEW

innodisk

REVENUE

NT\$ 35.62B
(2026 1H)

CAPITAL

NT\$964M

EPS

NT\$166.45
(2026 1H)

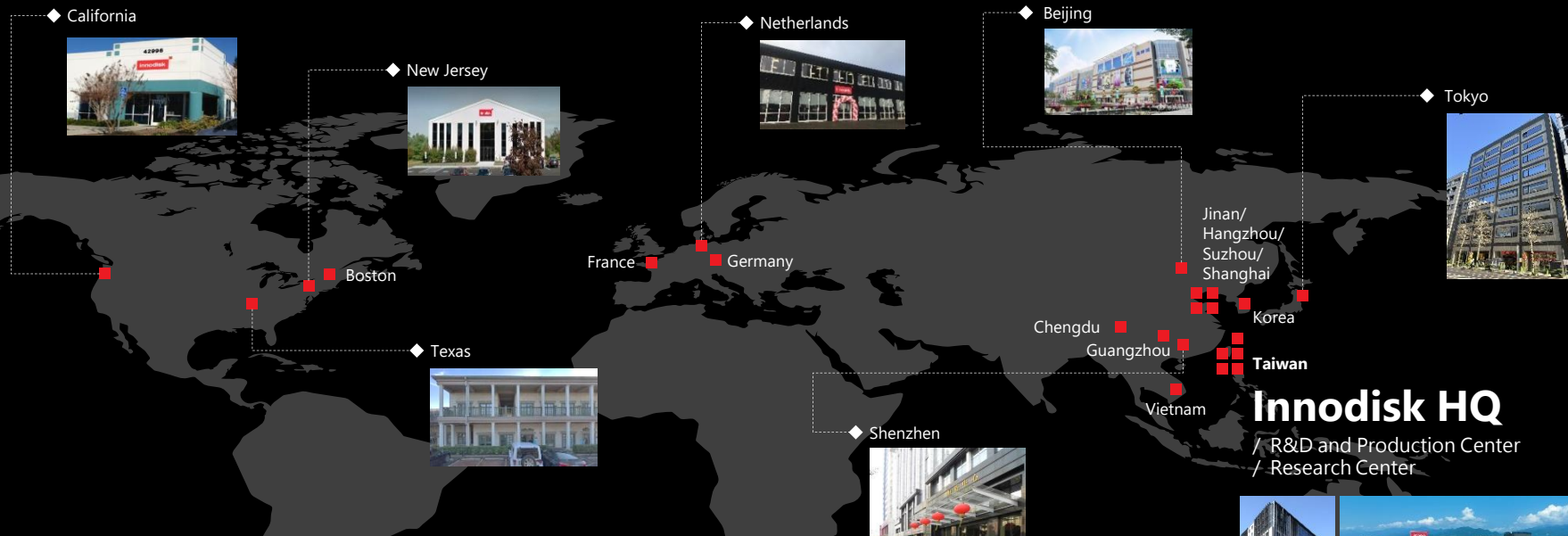
PATENTS

211

CUSTOMERS

4,000+

GLOBAL BUSINESS OPERATIONS



Locations

25

Employees

1,259

Taiwan: 1,111 / Overseas: 148

Lot Size
(Sq. Meter)

27,000

Floor Area:
1st building (Sq. Meter)

12,000

Floor Area:
2nd building (Sq. Meter)

15,000

Edge AI System and Solution
Edge AI Embedded Peripheral
Edge AI Camera Module

2026 Capacity
(SMT x 6)

1,080K

Maximum Capacity
(SMT x 8)

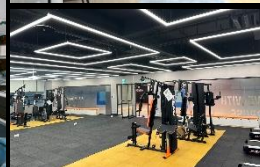
1,440K



YILAN SCIENCE PARK

R&D & MANUFACTURING CENTER

SPACE

Total :19,800 m²**17F** 1,650 m² / Aetina**16F** 3,300 m² / R&D Center, Sports & Activity Center, Training Room**7F** 3,300 m² / Aetina 660 m²**5F** 3,300 m²**4F** 3,300 m²**3F** 3,300 m²**2F** 1,650 m² / Aetina 660 m²**INNODISK
HEADQUARTERS**



PRODUCTION

1,440K / Maximum Capacity (SMT x 8)

CERTIFICATIONS

ISO9001 / ISO14001 / ISO45001 /
QC080000 / ISO14064-1 /
ISO27001 / IEC62443-4-1

MANUFACTURING

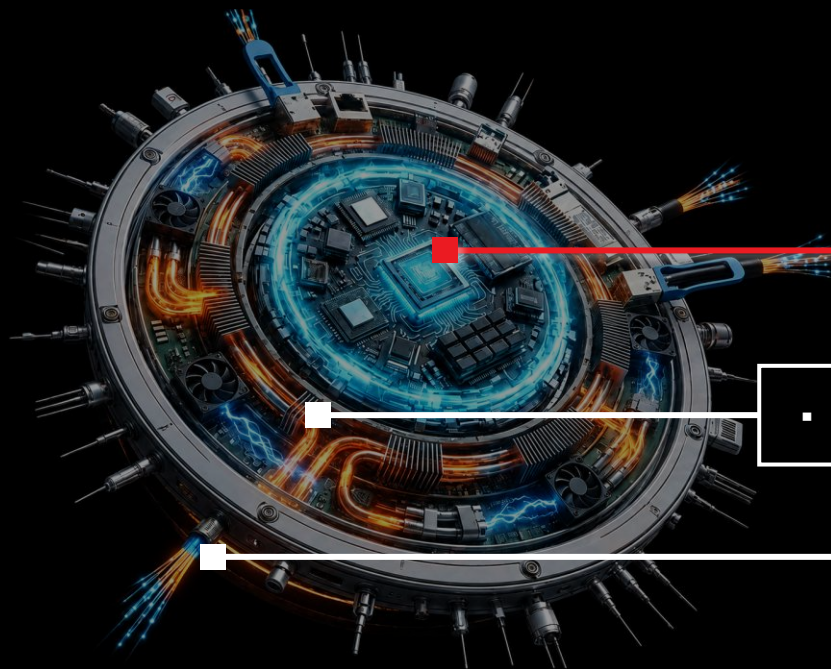
New Taipei City / Yilan County



QUALITY & SUSTAINABILITY: OUR TOP PRIORITY

MARKET TREND & PRODUCT STRATEGY

AI CORE: COMPUTING, MEMORY, STORAGE



innodisk

Innodisk Group: Comprehensive AI Core Architecture

- **Compute:** CPU / GPU / NPU / AI ASIC
- **Memory:** DRAM Module
- **Storage:** Flash Storage

- **Power:** Thermal & Energy Management

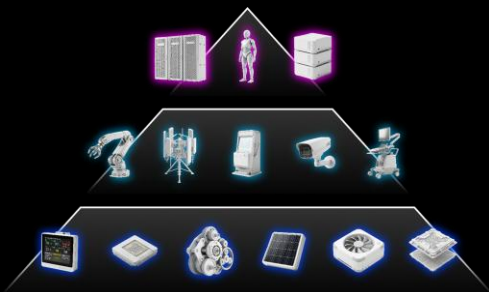
- **Connectivity:** Optical Communication

3 CORE VALUES: Market & Product Technology

01

Market & Application Value

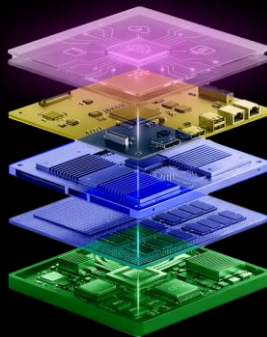
AI redefines value creation across products, services, and operations, driving unprecedented leaps in industry value.



02

Product Technology & Talent Value

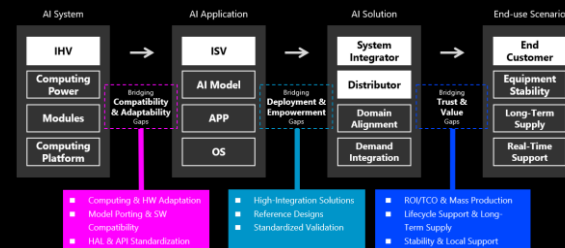
Deploying a robust five-layer AI architecture and expert talent to deliver highly compatible, collaborative solutions for diverse global needs.



03

Edge AI Integration & Deployment Value

Bridging technology gaps with strong R&D capabilities and global partnerships to connect edge applications and accelerate rapid Edge AI deployment.

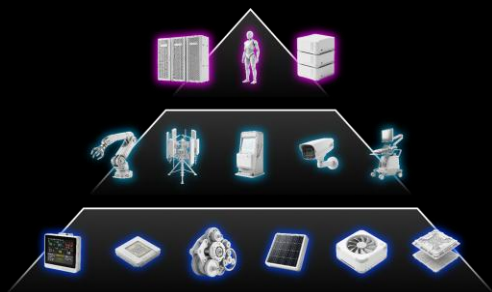


3 CORE VALUES: Market & Product Technology

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Market & Application Value

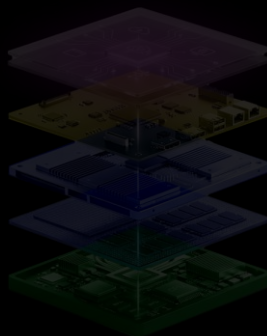
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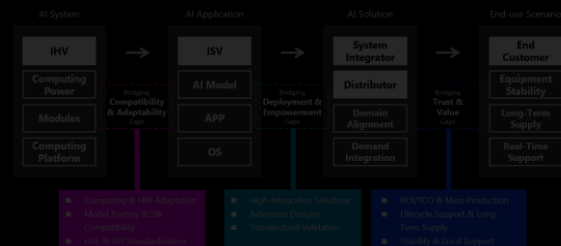
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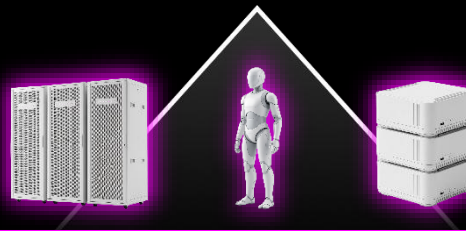
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01 Market & Application Value

AI Infrastructure

- GPU Server / Networking Switch / Router
- Humanoid Robot / Autonomous



Global Vertical Leaders

- Medical / 5G / Surveillance / Entertainment / Automation
- Tier-1 Market Leaders



High Value-added Industrial Solution Providers

- Manufacturing / Retail & Logistic / Smart Energy / Health Care / Communication / Entertainment / Enterprise



01 Market & Application Value

AI Infrastructure



Core Infrastructure for AI Computation, Smart Storage, Transmission, and Scaled Deployment

CSP / Data Center / AI Computing

Expanding AI training and inference fuel exponential growth in demand for high-performance computing, high-bandwidth transmission, and large-scale storage.

Optical & Network Communications

Exploding AI data traffic drives demand for low-latency, high-reliability transmission, backed by robust optical and network infrastructure to support heavy AI workloads.

Robotics & Physical AI

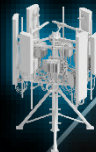
AI is moving from the digital realm to the physical world, empowering robotics and physical AI to integrate into everyday operations through perception, computing, and autonomous decision-making.

Enterprise AI

Enterprises are rapidly adopting generative AI to turn data into business insights while balancing data privacy, governance, and operational efficiency.

01 Market & Application Value

Global Vertical Leaders



Driving Market Standards and Industry Innovation for Scaled Edge AI Deployment

Healthcare

AI accelerates smart diagnostics, treatment, and care to boost precision and efficiency, driving the scaled adoption of advanced medical devices and services.

Networking & Telecom

AI enables real-time network analysis, smart traffic routing, and automated operations to enhance connectivity and power real-time decision-making.

Security & Surveillance

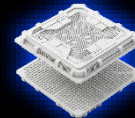
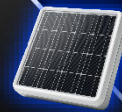
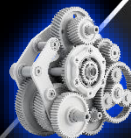
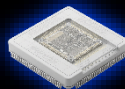
AI vision strengthens real-time recognition, event forecasting, and decision support, shifting security from passive recording to proactive prevention.

Smart Manufacturing

Transitioning from automation to AI-driven manufacturing, leveraging AI vision and robotics to massively boost overall production efficiency.

01 Market & Application Value

High Value-added Industrial Solution Providers



Domain Expertise for 4,000+ Global Customers, Accelerating High-Value AI Deployment

Deep Domain Know-How

Complex industrial environments require deep industry insight and application experience to address diverse operational conditions.

High Customization & Integration

Fragmented hardware specs and system architectures demand flexible, tailored hardware-software integration for successful project deployment.

High Value-Added

Growing demand for product differentiation and intelligence makes AI a key driver for equipment upgrades and competitive edge.

Long Lifecycle

Industrial equipment requires rigorous validation and extended lifecycles, demanding uncompromising reliability and supply stability.

3 CORE VALUES: Market & Product Technology

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Market & Application Value

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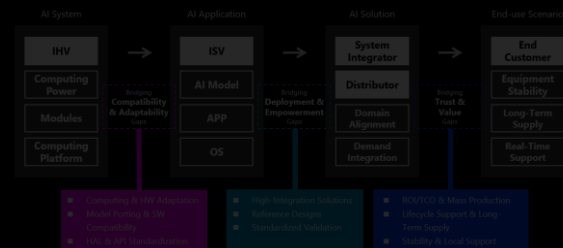
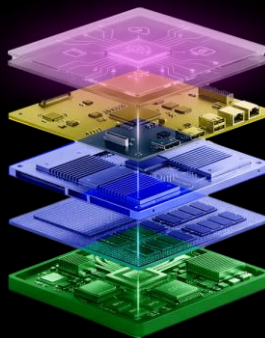
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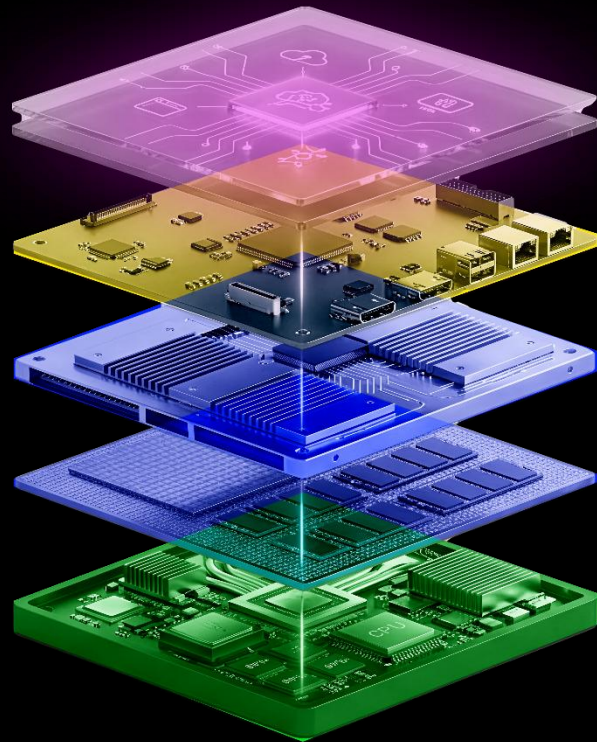
■ **Stack 5: Software**

■ **Stack 4: Sensing & Comm.**

■ **Stack 3: Storage**

■ **Stack 2: Memory**

■ **Stack 1: Compute**



02 Product Technology & Talent Value

Five-Layer Stack × Proprietary Tech Across All Layers

Stack 5: Software

Stack 4: Sensing & Comm.

Stack 3: Storage

Stack 2: Memory

Stack 1: Compute

**Heterogeneous
Core Computing
Power**

Reliable platforms,
industrial memory and
high-end storage

**Industrial
Module
Integration**

AI accelerator,
network and video
capture cards with
flexible I/O

**Custom
System Design**

Industrial structure
and thermal design
to speed up time-to-
market

**In-House
Firmware
Value-Add**

BIOS / BMC / MCU
system-level
optimization and
customization

**Rapid
Deployment**

End-to-end solutions defined by
field needs, solving real pain points

02 Product Technology & Talent Value

Five-Layer Stack × Proprietary Tech Across All Layers

Stack 5: Software

Stack 4: Sensing & Comm.

Stack 3: Storage

Stack 2: Memory

Stack 1: Compute

**Resilient
Vendor
Supply Chain**

Original Grade DRAM IC &
Strategic Sourcing

**Industrial
High-Grade
Components**

Industrial Quality &
Smart Manufacturing

**First-to-
Market**

Advanced R&D &
Specialized Solutions

**Rigorous
Validation &
Testing**

Key Components &
Hardware Integration

**Global
Localized
Support**

Global Services &
Warranty

02 Product Technology & Talent Value

Five-Layer Stack × Proprietary Tech Across All Layers

Stack 5: Software

Stack 4: Sensing & Comm.

Stack 3: Storage

Stack 2: Memory

Stack 1: Compute

**Strategic
Ecosystem
Partners**

Original Tier-1 key
components

**100% In-
House R&D**

Powered by proprietary, high-
precision test platforms

**Industrial
R&D Team**

20+year R&D team

**Cross-Domain
HW/FW
Integration**

Full-Spectrum Design
Validation

**Full Life-Cycle
Warranty**

Tailored engineering support
throughout the product lifecycle

02 Product Technology & Talent Value

Five-Layer Stack × Proprietary Tech Across All Layers

Stack 5: Software

Stack 4: Sensing & Comm.

Stack 3: Storage

Stack 2: Memory

Stack 1: Compute

Cross-Platform Design

X86, Nvidia, Qualcomm, AI ASIC

In-House Driver / FW

Easy to integrate with hardware and software

High-Speed Transmission & Smart Connectivity

AI connectivity and data transmission

Custom Sensor Solutions

In house R&D customization

Multi-Interface & Multi-Form-Factor Design

LAN, Optical, Serial, CAN, EtherCAT with PCIe, M.2 FF

02 Product Technology & Talent Value

Five-Layer Stack × Proprietary Tech Across All Layers

Stack 5: Software

Cloud Device Management

iCAP, OTA, OOB
remote management

API / SDK Support

Friendly Utility Support

BIOS / BSP / Driver Customization

In-house R&D support customization

Model Inference & Training Tools

iVIT-T & iVIT-I Tool Kits

AI Engine

MCP protocol expedite
Agentic AI

Stack 4: Sensing & Comm.

Stack 3: Storage

Stack 2: Memory

Stack 1: Compute

02 Product Technology & Talent Value

Five-Layer Stack × Proprietary Tech Across All Layers

Stack 5: Software

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Strategic Ecosystem Partners

Original Tier-1 key components

Resilient Vendor Supply Chain

Original Grade DRAM IC & Strategic Sourcing

Heterogeneous Core Computing Power

Reliable platforms, industrial memory and high-end storage

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Industrial High-Grade Components

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Industrial Module Integration

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Multi-Interface & Multi-Form-Factor Design

LAN, Optical, Series, CAN, EtherCAT with PCIe, M.2 FF

Full Life-Cycle Warranty

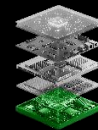
Tailored engineering support throughout the product lifecycle

Global Localized Support

Global Services & Warranty

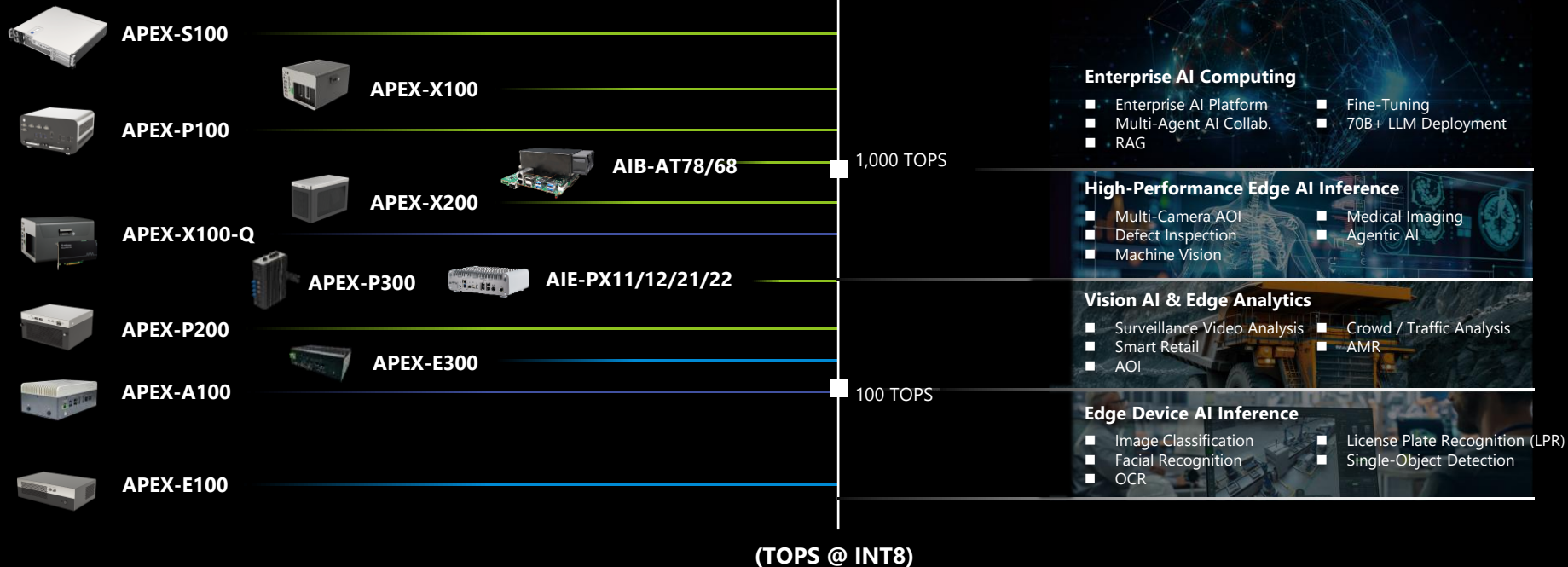
Rapid Deployment

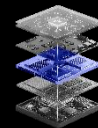
End-to-end solutions defined by field needs, solving real pain points



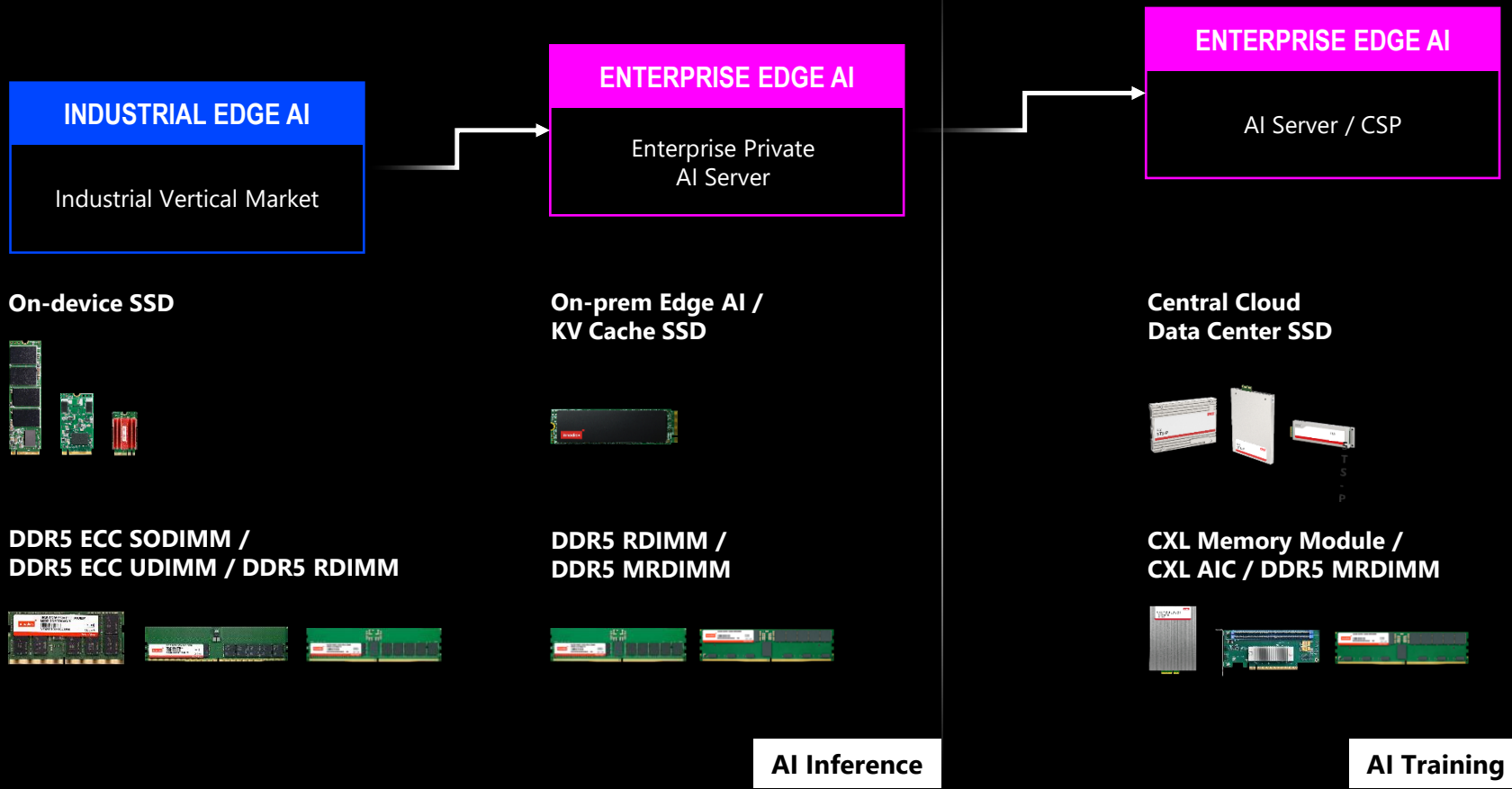
Stack 1: Compute

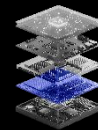
Powered by  NVIDIA  Qualcomm  Intel





Stack 2 & 3: Memory & Storage

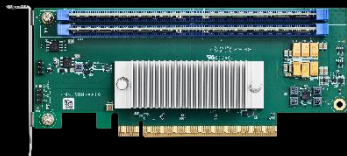




Stack 2: Memory

BREAKING AI ARCHITECTURE BOTTLENECKS

CXL AIC (ADD-IN-CARD) Breaking Edge Computing's Memory Barrier



- **Objective:** Expand memory capacity for the next-gen AI.
- **Key Feature:** Seamless, large-scale memory scaling.
- **Benefit:** Optimized TCO for Hyperscale Data Centers & AI Training.

EMPOWERING EDGE AI COMPUTING

DDR5 8000MT/s RDIMM Edge AI Ultra-High-Speed Computing Engine



- **Target:** Edge AI & high-speed networking bandwidth.
- **Performance:** Ultra-low latency & superior stability.
- **Application:** Real-time edge inference & massive data processing.

DRAM Module Portfolio

AI Memory



Embedded Memory



Server Memory



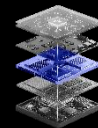
Wide Temp. Memory



Customized Memory



- **Formfactor:**
CMM2 / CUDIMM / CSODIMM / SODIMM / RDIMM / VLP /
- **Technology & Generation:**
CXL / DDR5 / DDR4 / DDR3 / DDR2



Stack 3: Storage

PCIe Gen5 & 218-layer 3D NAND Flash

MAXIMIZING SYSTEM BOOT RELIABILITY

DATACENTER SSD | BOOT DRIVE

PCIe Gen5, 5TS4-P Series: E1.S and U.2



- **Optimized Booting:** High-speed startup and OS loading.
- **Reliability:** High endurance for frequent write cycles.

ACCELERATING LARGE-SCALE DATA THROUGHPUT

DATACENTER SSD | STORAGE DRIVE

PCIe Gen5, 5TS-P Series: U.2, EDSFF (E3.S, E3.L and E1.S)



- **High Throughput:** Designed for large-scale data handling and sustained performance.
- **Low Latency:** Scalable for heavy processing and storage.

Flash Storage (SSD) Portfolio

PCIe



USB



SD



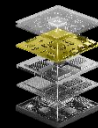
PATA



SATA



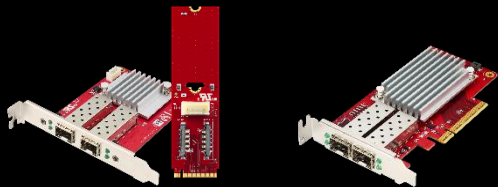
- **Embedded Product Line:**
M.2 / U.2 / CFexpress / EDSFF / 2.5" / 1.8" / SATA Slim /
SATADOM / mSATA / CFast / nanoSSD / CompactFlash Card /
SD Card & MicroSD Card / USB / USB EDC



Stack 4: Sensing & Comm.

REVOLUTIONIZING COMPACT SYSTEM BOOTING

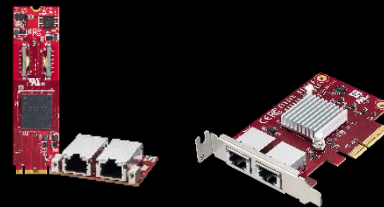
10GbE / 25GbE OPTICAL LAN MODULES



- **Space-Efficient:** World's First M.2 Optical LAN Module Family for compact systems.
- **High-Speed Transfer:** Fast, stable data transfer for higher throughput.

ENHANCING HIGH-EFFICIENCY DATA EXCHANGE

10GBE RJ45 LAN MODULE



- **Industrial-Grade:** World's First Industrial-Grade 10GbE LAN Module.
- **Low-Latency:** Real-time data transfer for high-performance applications.

Intelligent Peripheral Solution Portfolio

LAN



CAN Bus & CAN FD

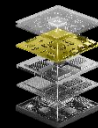


Serial



Wi-Fi





Stack 4: Sensing & Comm.

RUGGEDIZED LONG-RANGE VISION & CLARITY

GMSL2 CAMERA SERIES

High-bandwidth, long-range, and low-latency transmission

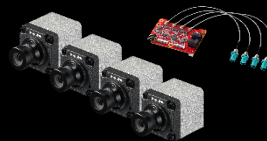


- **IP67/IP69K Ruggedized:** Maximum dust, water proof.
- **15m Long-Reach:** Stable performance over extended distances.
- **On-board ISP:** Superior image quality and professional control.
- **NVIDIA Jetson & Raspberry Pi Ready:** Support for leading AI platforms.

REDEFINING THE EDGE AI VISION STANDARD

INNODISK VISION SOLUTION: BUNDLE PACKAGE

Seamless Integration. Rapid Deployment.
Proven Performance



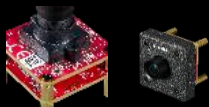
- **Unified Hardware Bundle:** Pairs GMSL2 camera and capture card for seamless evaluation.
- **Seamless Integration:** Pre-validated design eliminates compatibility friction.
- **Accelerated Development:** Focus directly on vision software and rapid deployment.
- **Superior Performance:** Delivers sharp image quality and stable GMSL2 signal integrity.

Camera Module Portfolio

USB 2.0



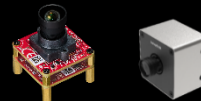
MIPI CSI-2



GMSL2

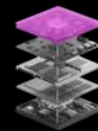


MIPI over Type-C



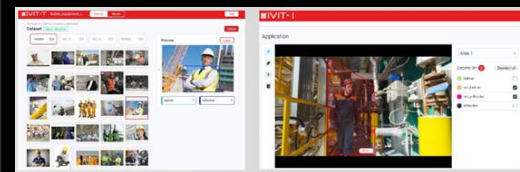
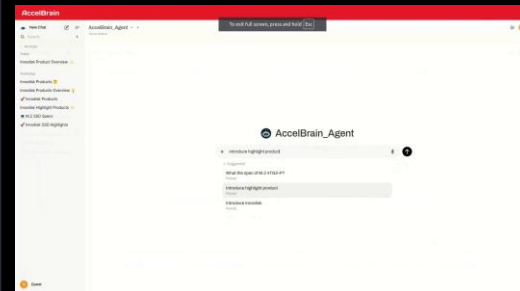
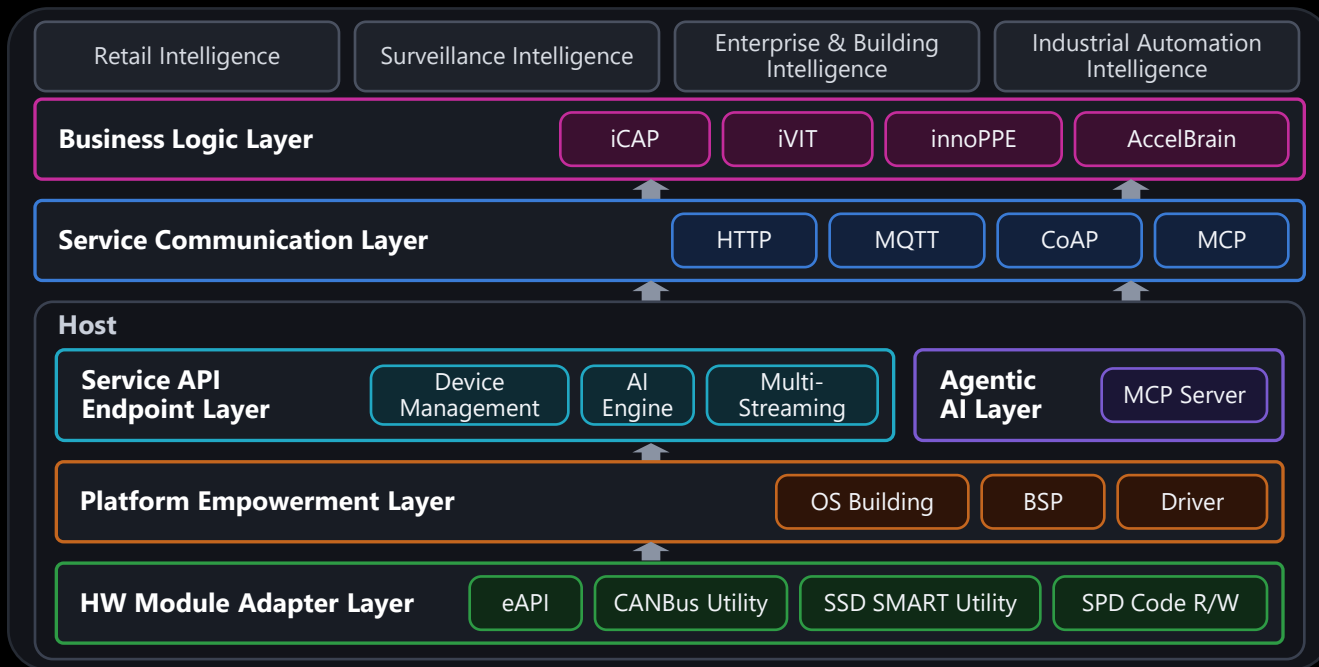
Capture Card





Stack 5: Software

INNOVATING IN SOFTWARE. ELEVATING VALUE AT THE EDGE.



3 CORE VALUES: Market & Product Technology

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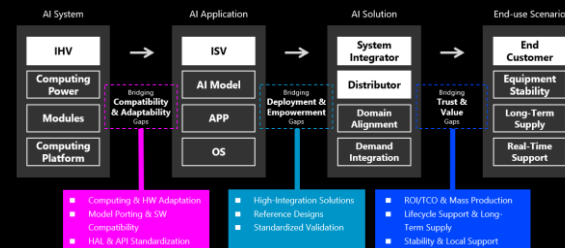
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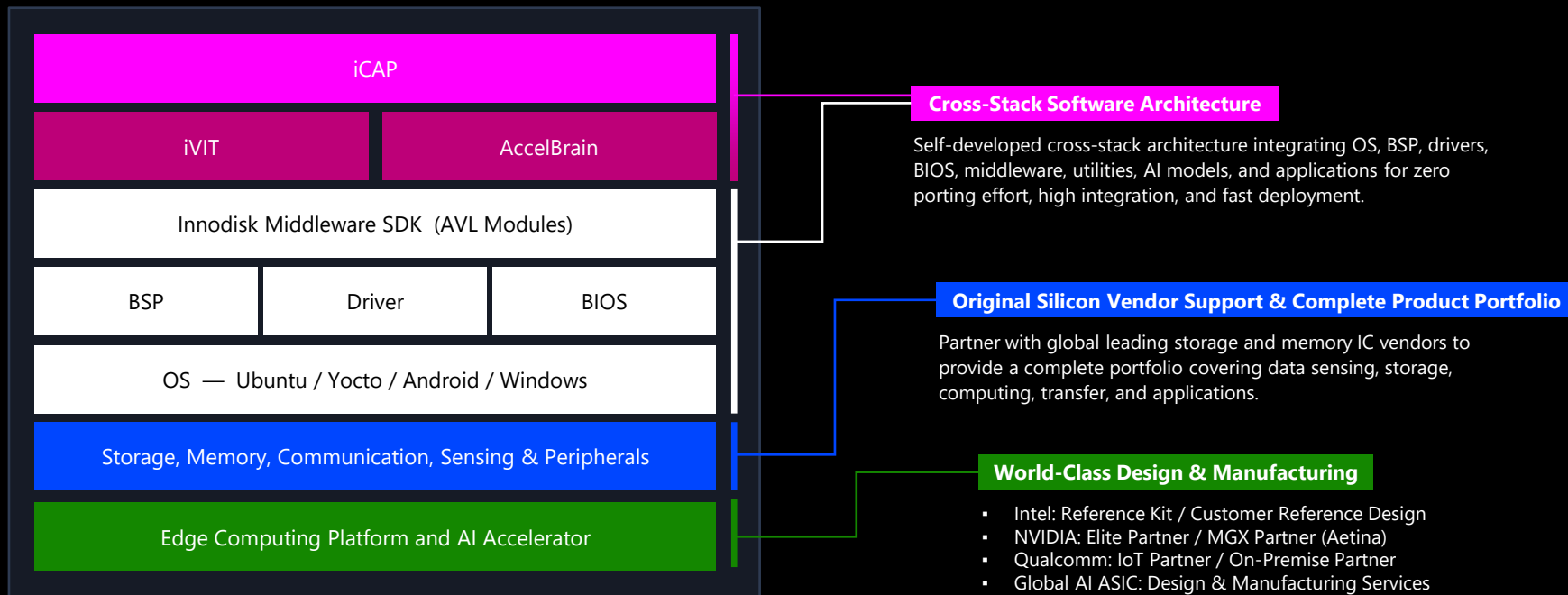
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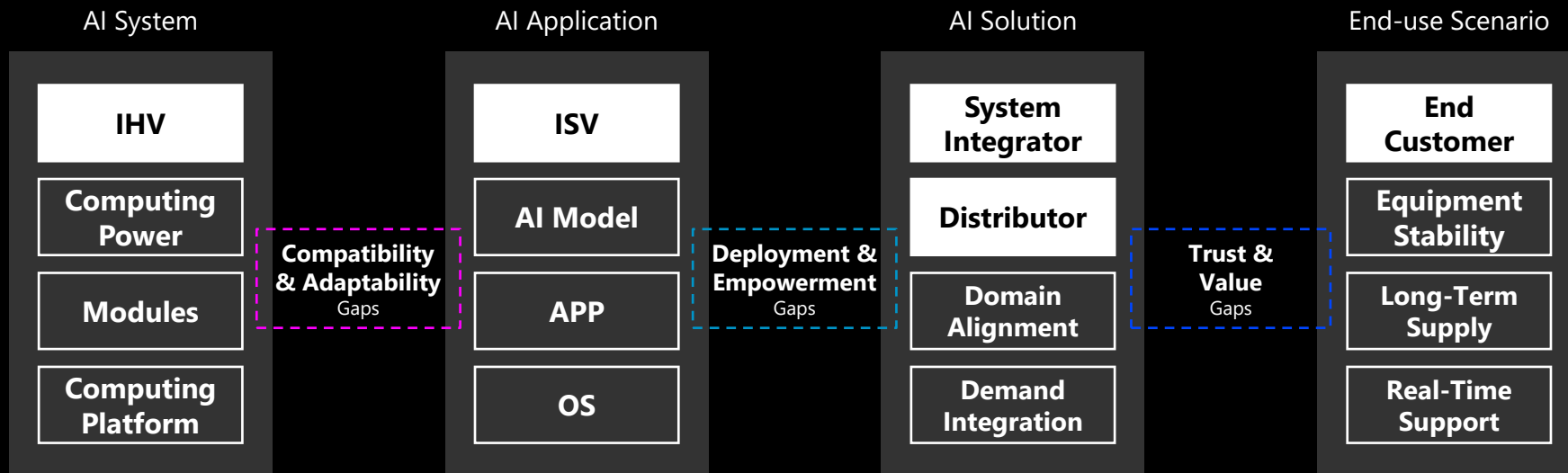
03 Edge AI Integration & Deployment Value

Bridging Tech Gaps to Minimize Client Integration Effort



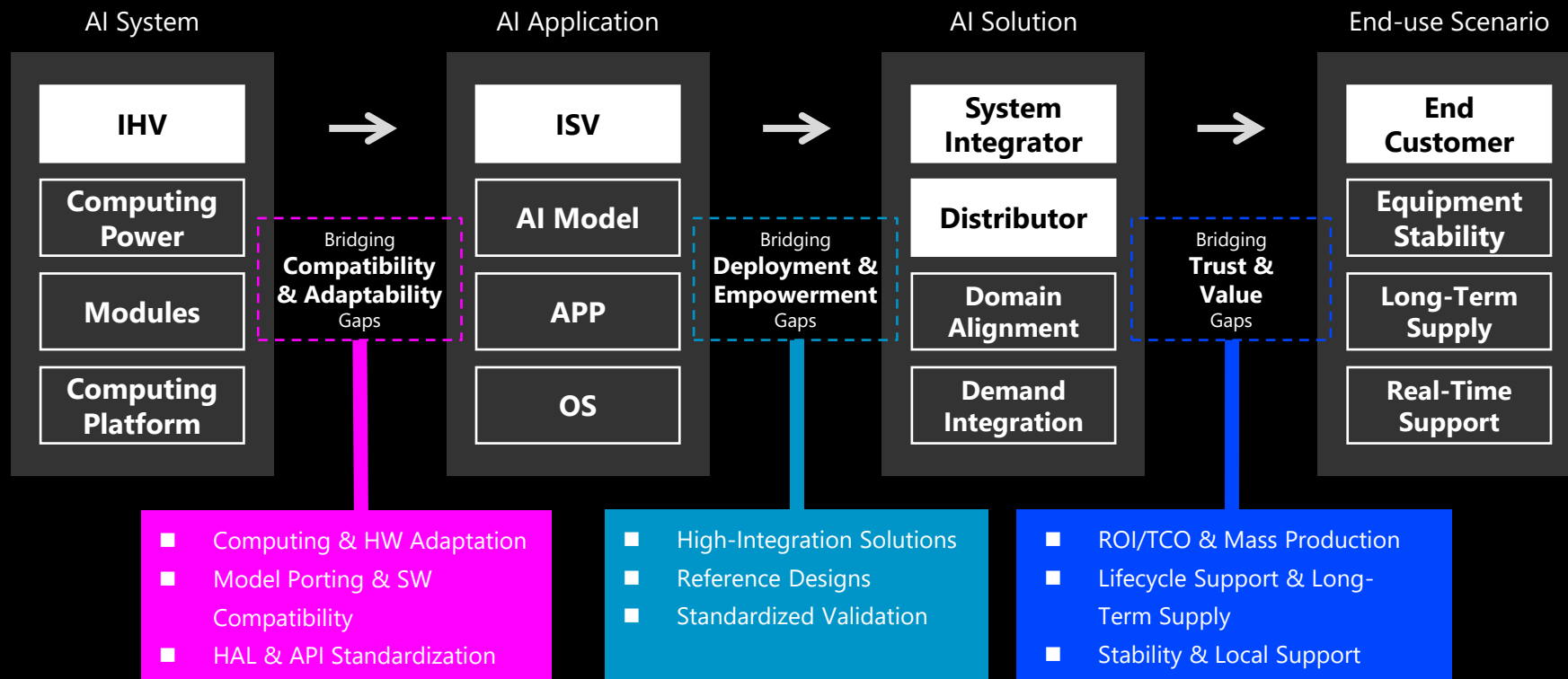
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03 Edge AI Integration & Deployment Value

Bridging Tech Gaps to Minimize Client Integration Effort





SOFTWARE / FIRMWARE	Cloud AI Platform	iCAP												
	AI-Stack SDK	AccelBrain, AccelTune, IQ Studio, iVIT												
	Software Tools	iSeries Software												
	OS & Middleware	Windows, Linux, BSP, eAPI, Drivers												
AI ACCELERATOR	NVIDIA			Intel			Qualcomm			AI ASIC				
AI PLATFORM	x86						ARM							
	Intel Atom x6000 / 7000		Intel 12 / 13 / 14 th Gen Core-i		Intel Core Ultra Series1 / 2 / 3		Intel Xeon 6		NVIDIA Jetson Orin / Thor		Qualcomm Dragonwing IQ 9 / 8 / X		NXP i.MX 8M Plus / 95	
AI Storage / Memory	Flash													
	DRAM													
AI Peripheral	Camera					LAN								
	Display			Air Sensor / Gas Sensor				Wireless						
	Storage			CAN Bus / CAN FD				Serial						
		Device Management Monitoring / OTA / Diagnostics												
		Inference & Tuning Model Deployment / Training / Optimization												
		Runtime & System Support OS Porting / Runtime Support / Pre-Configured System / eAPI Hardware Control / Software Configuration												
		Data Management Firmware Customization / Health Monitoring / Encryption & RAID												
		Sensing & Communication Vision Input / Transmission / Real-Time Control												

Market & Application Value

AI Infrastructure

- GPU Server / Networking Switch / Router
- Humanoid Robot / Autonomous

An illustration featuring a 3D bar chart with four bars of increasing height, a small robot standing on the top bar, and a server rack in the background.

Exponential Growth

Global Vertical Leaders

- Medical / 5G / Surveillance / Entertainment / Automation
- Tier-1 Market Leaders

An illustration showing a robotic arm holding a flag, a satellite in orbit, and various industrial and medical equipment on the ground.

Global Market Leader

High Value-added Industrial Solution Providers

- Manufacturing / Retail & Logistic / Smart Energy / Health Care / Communication / Entertainment / Enterprise

An illustration showing three stylized human figures standing together, with various industrial and technological components like gears and a robot in the background.

4,000+ High-value Customer Base



Phase 1
2018 (In Operation)

Phase 2
2024 (In Operation)

Phase 3
2026 Q4 (Scheduled to Break Ground)

**Innodisk R&D and Production Center
Construction of Phase 3 Building and Dormitory**

Innodisk R&D & Manufacturing center
Construction of Phase 3 Building and Dormitory
Scheduled to Break Ground in 2026 Q4



Phase 3

Phase 2

Phase 1

Dormitory



Phase 3

Dormitory

Phase 1



AI IN ACTION GLOBAL CAMPAIGN

COMPUTEX 2026

@TAIWAN, TAIPEI



INNODISK AI IN ACTION

Promote AI solutions with global partners



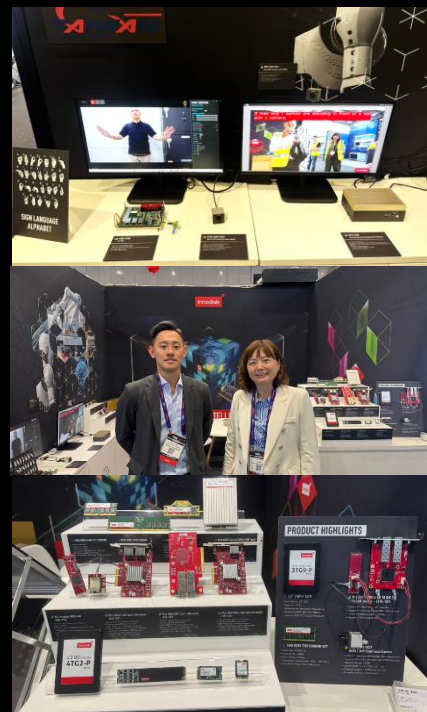
AI EXPO @Taiwan



IT Week @Japan



Automate @USA



Hardware Pioneer Max @United Kindom

ESG COMMITMENT

ACHEIVEMENTS & HIGHLIGHTS

- Maintaining a Corporate Governance Evaluation between **6% to 20%**.
- Approved by the Board of Directors, the company has set its Net Zero Emission Pathway, marking a proactive step toward long-term net-zero transition.
- Established the “**Sustainability Development & Information Security Committee**” to enhance ESG commitment.
- Received the EcoVadis Bronze Medal, CommonWealth Sustainability Awards, and the Parenting Family-Friendly Workplace Award, reflecting Innodisk’s well-rounded achievements in sustainability.

ECOLOGICAL HARMONY

Wuweigang Waterbird reserve: Biodiversity Three-Year Project

- Partner with local organizations on habitat protection, invasive species removal, and little tern conservation.
- Advance ecological monitoring and environmental education to foster a thriving, biodiverse ecosystem with stakeholders.

Yue-Ming School: Three-Year Ocean Activists Program

- Connect academia and local communities to cultivate future ocean advocates and strengthen social impact.
- Build sustainability awareness through school-based conservation workshops and projects.

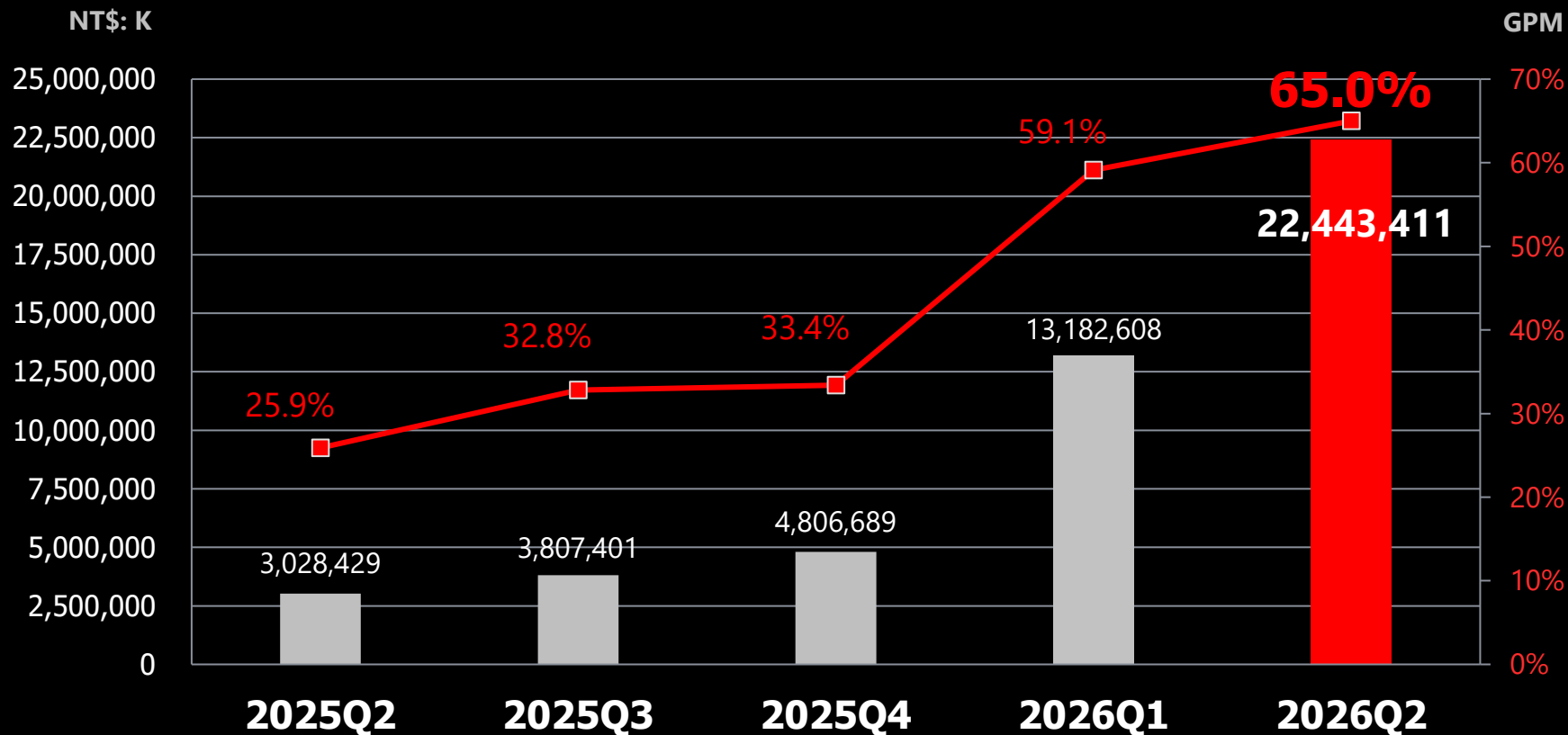


宜鼎國際 永續之路

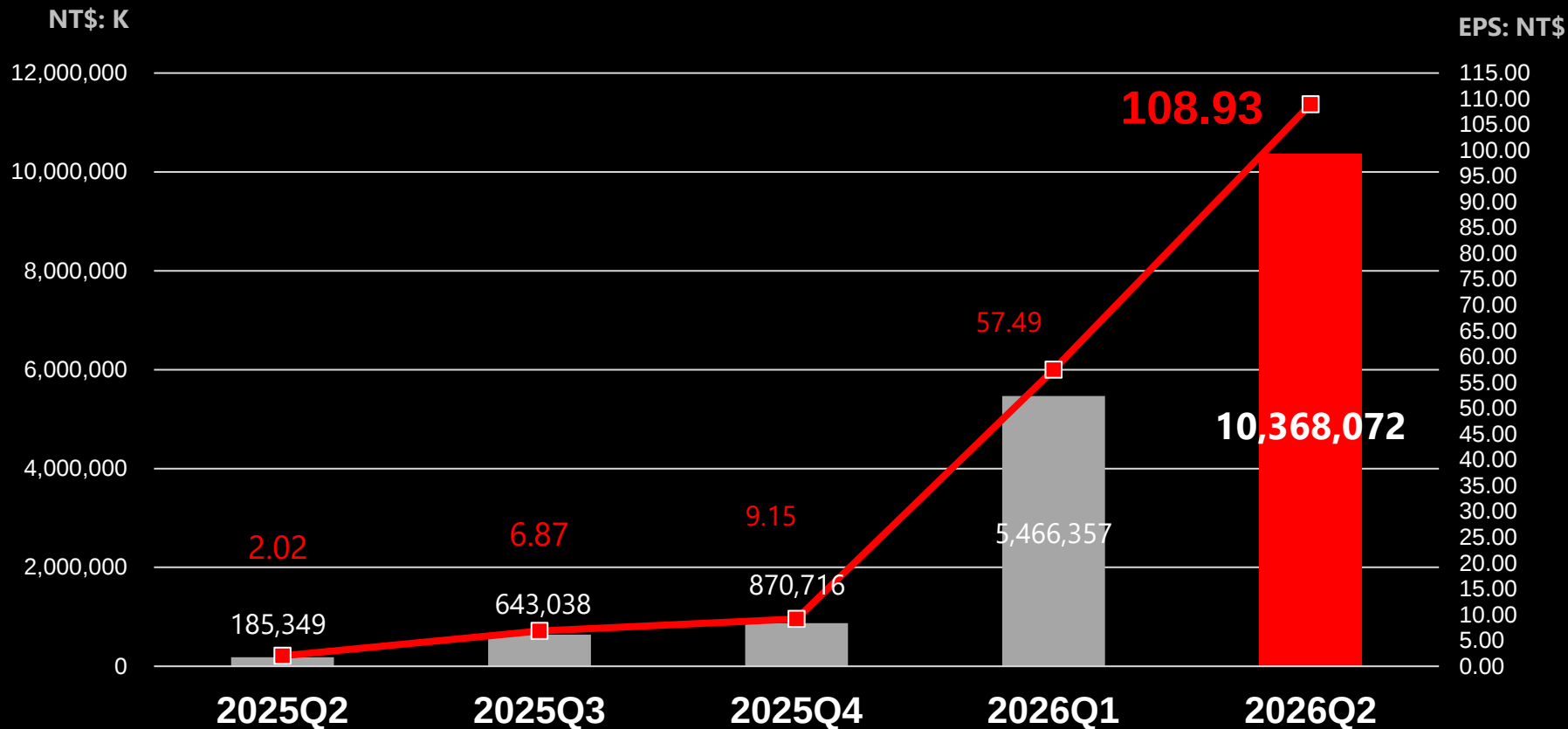


FINANCIAL INFORMATION

Revenues and GPM over last 5 quarters

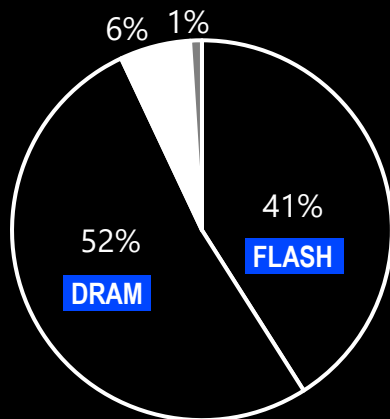


Net Profits and EPS over last 5 quarters

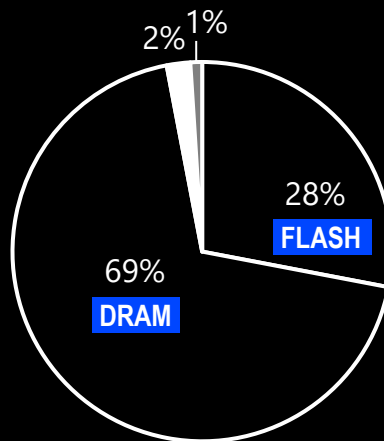


Revenue Breakdown by Product Lines

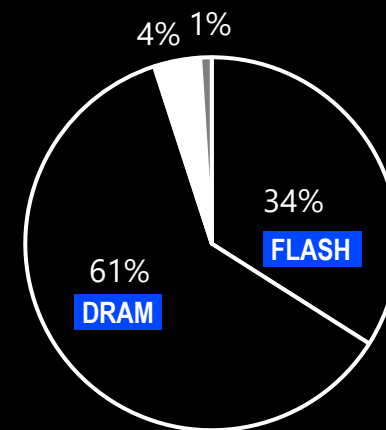
2025Q2



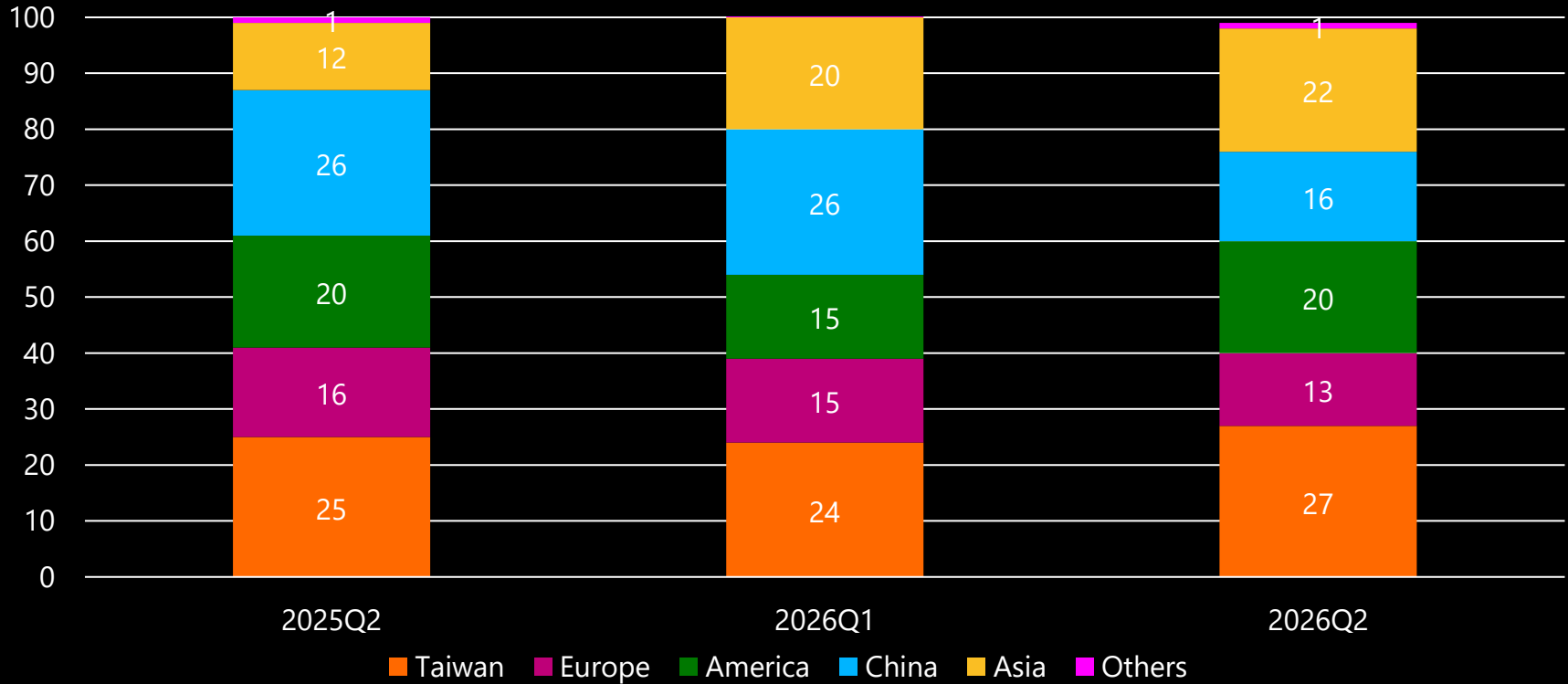
2026Q1



2026Q2

 DRAM FLASH AI Solutions Others

Revenue Breakdown by Regions



2026Q2 Operating Results

	2026Q2	2026Q1	QoQ	2025Q2	YoY
Revenues	22,443,411	13,182,608	70.3%	3,028,429	641.1%
Cost of good sold	7,853,799	5,391,251	45.7%	2,243,340	250.1%
Gross profit	14,589,612	7,791,357	87.3%	785,089	1758.3%
Operation expenses	1,443,892	941,157	53.4%	431,279	234.8%
Operation profits	13,145,720	6,850,200	91.9%	353,810	3615.5%
Non-operating income and expenses	68,664	66,827	2.7%	-126,311	-154.4%
Profit before tax	13,214,384	6,917,027	91.0%	227,499	5708.5%
Income tax expense	2,808,521	1,439,498	95.1%	53,708	5129.2%
Net profits	10,405,863	5,477,529	90.0%	173,791	5887.6%
Non-controlling interests	37,791	11,172	238.3%	-11,558	-427.0%
Net profit attributable to parent company	10,368,072	5,466,357	89.7%	185,349	5493.8%
EPS	108.93	57.49		2.02	
Gross margin	65.0%	59.1%		25.9%	
Operating margin	58.6%	52.0%		11.7%	
Net profit rate	46.4%	41.6%		5.7%	

Q&A



innodisk

ARCHITECT INTELLIGENCE